



Product Change Notification: DSNO-09UULT882

Date:

07-Oct-2026

Product Category:

32-Bit Microcontrollers

Notification Subject:

CCB 7322.004 Final Notice: Qualification of MTAI as an additional assembly site for
ATSAMD21G17D-OAZ, ATSAMD21J17D-OAZ, ATSAMD21G17D-OAZT, ATSAMD21G17D-AZ,
ATSAMD21G17D-AF, ATSAMD21G17D-AZT, ATSAMD21G17D-AFT, ATSAMD21G17D-AUT,
ATSAMD21G17D-AU, ATSAMD21J17D-AFT, ATSAMD21J17D-AZT, ATSAMD21J17D-AZ,
ATSAMD21J17D-AF, ATSAMD21J17D-AUT and ATSAMD21J17D-AU catalog part numbers (CPN)
available in 48L TQFP (7x7x1.0 mm) and 64L TQFP (10x10x1.0mm) packages.

Affected CPNs:

[DSNO-09UULT882_Affected_CPN_10072026.pdf](#)

[DSNO-09UULT882_Affected_CPN_10072026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MTAI as an additional assembly site for ATSAMD21G17D-OAZ, ATSAMD21J17D-OAZ, ATSAMD21G17D-OAZT, ATSAMD21G17D-AZ, ATSAMD21G17D-AF, ATSAMD21G17D-AZT, ATSAMD21G17D-AFT, ATSAMD21G17D-AUT, ATSAMD21G17D-AU, ATSAMD21J17D-AFT, ATSAMD21J17D-AZT, ATSAMD21J17D-AZ, ATSAMD21J17D-AF, ATSAMD21J17D-AUT and ATSAMD21J17D-AU catalog part numbers (CPN) available in 48L TQFP (7x7x1.0 mm) and 64L TQFP (10x10x1.0mm) packages.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)

Assembly Site		ASE Group Chung-Li (ASCL)	ASE Group Chung-Li (ASCL)	Microchip Technology Thailand (HQ) (MTAI)	Yes
Moisture Sensitivity Level (MSL)		MSL-3	MSL-3	MSL-1	Yes
Wire Material		Au	Au	CuPdAu	Yes
Die Attach Material		EN-4900GC (PFAS Free)	EN-4900GC (PFAS Free)	QMI519 (PFAS Free)	Yes
Molding Compound Material		G700LA	G700LA	G700HA	Yes
Lead-Frame Material	48L TQFP (7×7×1.0 mm)	C194	C194	C7025	Yes
	64L TQFP (10×10×1.0 mm)	C194	C194	C0725	Yes
Lead-Frame Paddle Size	48L TQFP (7×7×1.0 mm)	197 x 197 mils	197 x 197 mils	200 x 200 mils	Yes
	64L TQFP (10×10×1.0mm)	200 x 200 mils	200 x 200 mils	200 x 200 mils	Yes
Lead-Frame DAP Surface Prep		Ag	Ag	Bare Copper	Yes
Lead-Frame Design		See Pre and Post Change Summary Attachment for Comparison.			

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying MTAI as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 04 December 2026 (date code: 2649)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	October 2026					>	December 2026				
Work Week	40	41	42	43	44		49	50	51	52	53
Qual Report Availability		x									
Final PCN Issue Date		x									
Estimated Implementation Date							x				

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Note: This is a qualification by similarity (QBS) to CCB# 7322.

Revision History: October 07, 2026: Issued final notification

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_DSNO-09UULT882_Qual_Report_CCB7322.pdf](#)

[PCN_DSNO-09UULT882_Pre_and_Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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